



**Pin Description<sup>(1)</sup>**

Pin #	Name	Type	Description
1	V <sub>DD</sub>	Power	Core Power Supply
2	CLK_SEL	Input	Clock select input. When high, selects CLK1 input. When low, selects CLK0 input. LVCMOS/LVTTL level with 50kΩ pull down.
3	CLK0	Input	Differential clock input with pull-down
4	/CLK0	Input	Inverting differential clock input. Defaults to V <sub>DD</sub> /2 if left floating.
5	V <sub>BB</sub> (NC)	Power	Internal Common Mode Voltage, can be left as not connected if unused.
6	CLK1	Input	Differential clock input with pull-down
7	/CLK1	Input	Inverting differential clock input. Defaults to V <sub>DD</sub> /2 if left floating.
8	V <sub>EE</sub>	Power	Connect to negative power supply
9, 16, 25, 32	V <sub>DDO</sub>	Power	Output Power pin
11, 10	Q9, /Q9	Output	Differential output pair, LVPECL interface level.
13, 12	Q8, /Q8	Output	Differential output pair, LVPECL interface level.
15, 14	Q7, /Q7	Output	Differential output pair, LVPECL interface level.
18, 17	Q6, /Q6	Output	Differential output pair, LVPECL interface level.
20, 19	Q5, /Q5	Output	Differential output pair, LVPECL interface level.
22, 21	Q4, /Q4	Output	Differential output pair, LVPECL interface level.
24, 23	Q3, /Q3	Output	Differential output pair, LVPECL interface level.
27, 26	Q2, /Q2	Output	Differential output pair, LVPECL interface level.
29, 28	Q1, /Q1	Output	Differential output pair, LVPECL interface level.
31, 30	Q0, /Q0	Output	Differential output pair, LVPECL interface level.

**Note:**

1. I = Input, O = Output, P = Power supply connection.

**Control Input Function Table**

CLK_SEL	Outputs
0	CLK0
1	CLK1

## Absolute Maximum Ratings<sup>(1)</sup>

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V <sub>DD</sub>	Supply voltage	Referenced to GND			4.6	V
V <sub>IN</sub>	Input voltage	Referenced to GND	-0.5		V <sub>DD</sub> +0.5V	V
I <sub>OUT</sub>	Surge Current				100	mA
T <sub>STG</sub>	Storage temperature		-55		150	°C
V <sub>BB</sub>	Sink/source Current, I <sub>BB</sub>		-0.5		+0.5	mA
T <sub>j</sub>	Junction Temperature				125	°C

### Note:

- Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These ratings are stress specifications only and correct functional operation of the device at these or any other conditions above those listed in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

## Operating Conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V <sub>DD</sub>	Core Power Supply Voltage		2.375		3.6	V
V <sub>DDO</sub>	Output Power Supply Voltage		2.375		3.6	V
T <sub>A</sub>	Ambient Temperature		-40		85	°C
I <sub>DD</sub>	Core Power Supply Current			70	95	mA
I <sub>DDO</sub>	Output Power Supply Current	All LVPECL outputs unloaded		110	200	

## LVCMOS/LVTTL DC Characteristics (T<sub>A</sub> = -40°C to +85°C, V<sub>DD</sub> = 3.3V ±10%, V<sub>DDO</sub> = 2.5V ±5% to 3.3V ±10%)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V <sub>IH</sub>	Input High Voltage	CLK_SEL		1.7	V <sub>DD</sub> +0.3	V
V <sub>IL</sub>	Input Low Voltage	CLK_SEL		-0.3		
I <sub>IH</sub>	Input High Current	CLK_SEL	V <sub>IN</sub> = V <sub>DD</sub> = 3.6V		150	μA
I <sub>IL</sub>	Input Low Current	CLK_SEL	V <sub>IN</sub> = 0V, V <sub>DD</sub> = 3.6V	-150		μA
R	Input Pullup/Pulldown Resistance			50		kΩ

**LVPECL DC Characteristics** ( $T_A = -40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ ,  $V_{DD} = 3.3\text{V} \pm 10\%$ ,  $V_{DDO} = 2.5\text{V} \pm 5\%$  to  $3.3\text{V} \pm 10\%$ )

Symbol	Parameter	Conditions	Min	Typ	Max	Units	
$I_{IH}$	Input High Current	CLK0, CLK1	$V_{IN} = V_{DD} = 3.6\text{V}$			150	$\mu\text{A}$
		/CLK0, /CLK1	$V_{IN} = V_{DD} = 3.6\text{V}$			150	$\mu\text{A}$
$I_{IL}$	Input Low Current	CLK0, CLK1	$V_{DD} = 3.6\text{V}$ , $V_{IN} = 0\text{V}$	-150			$\mu\text{A}$
		/CLK0, /CLK1	$V_{DD} = 3.6\text{V}$ , $V_{IN} = 0\text{V}$	-150			$\mu\text{A}$
$V_{CMR}$	Common Mode Input Voltage <sup>(1)</sup>		$V_{EE}+0.5$		$V_{DD}$	V	
$V_{OH}$	Output High Voltage <sup>(2)</sup>	$V_{DDO} = 2.5\text{V}$ or $3.3\text{V}$	$V_{DDO}-1.5$	$V_{DDO}-1.4$	$V_{DDO}-0.9$	V	
$V_{OL}$	Output Low Voltage <sup>(2)</sup>	$V_{DDO} = 2.5\text{V}$ or $3.3\text{V}$	$V_{DDO}-2.2$	$V_{DDO}-2.0$	$V_{DDO}-1.7$	V	
R	Input Pullup/Pulldown Resistance			50		k $\Omega$	

**Notes:**

- For single-ended applications, the maximum input voltage for CLK and /CLK is  $V_{DD}+0.3\text{V}$
- Outputs terminated with  $50\Omega$  to  $V_{DD}-2.0\text{V}$

**AC Characteristics** ( $T_A = -40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ ,  $V_{DD} = 3.3\text{V} \pm 10\%$ ,  $V_{DDO} = 2.5\text{V} \pm 5\%$  to  $3.3\text{V} \pm 10\%$ )

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$f_{max}$	Output Frequency				1500	MHz
$t_{pd}$	Propagation Delay <sup>(1)</sup>			1200		ps
$T_{sk}$	Output-to-output Skew <sup>(2)</sup>			40		ps
$t_r/t_f$	Output Rise/Fall time	20% - 80%		150		ps
$t_{odc}$	Output duty cycle	$f \leq 650\text{ MHz}$	48		52	%
$V_{PP}$	Output Swing	LVPECL outputs	0.6	1.0		V
$t_j$	Buffer additive jitter RMS	156.25MHz (12KHz-20MHz integration range) Input condition per Phase Noise and Additive Jitter Plot below		0.03	0.05	ps

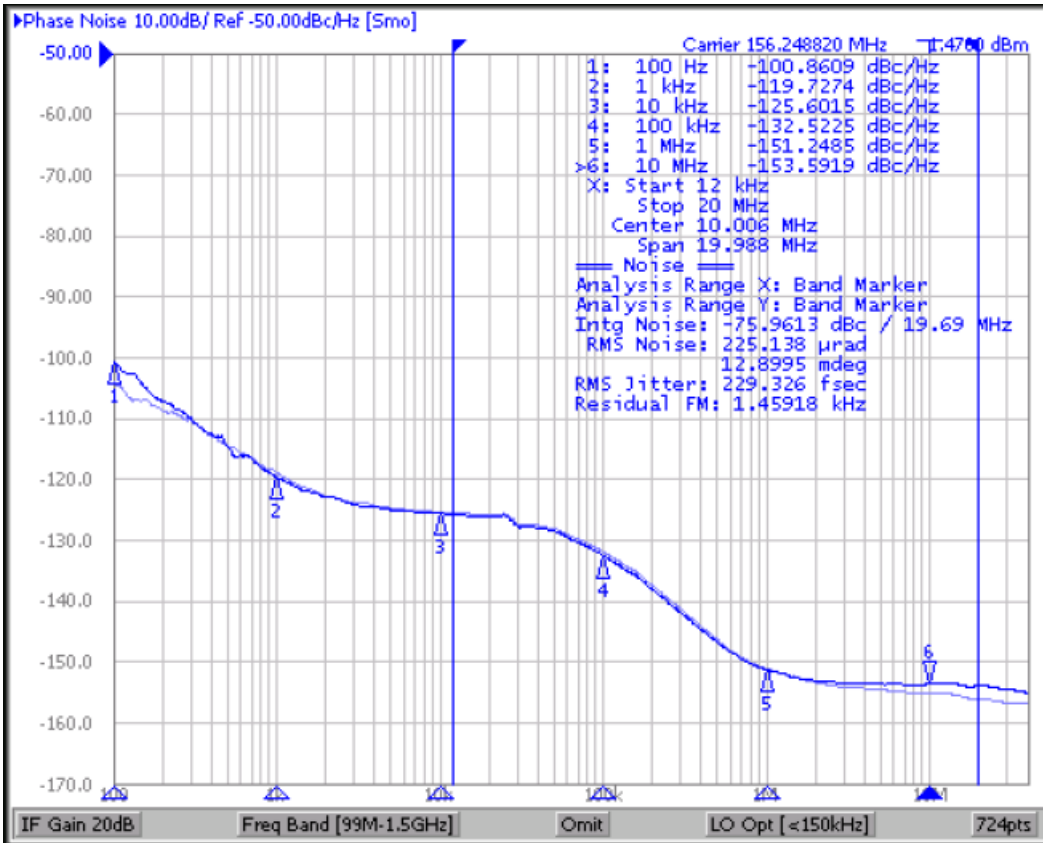
**Notes:**

- Measured from the differential input to the differential output crossing point
- Defined as skew between outputs at the same supply voltage and with equal loads. Measured at the output differential crossing point

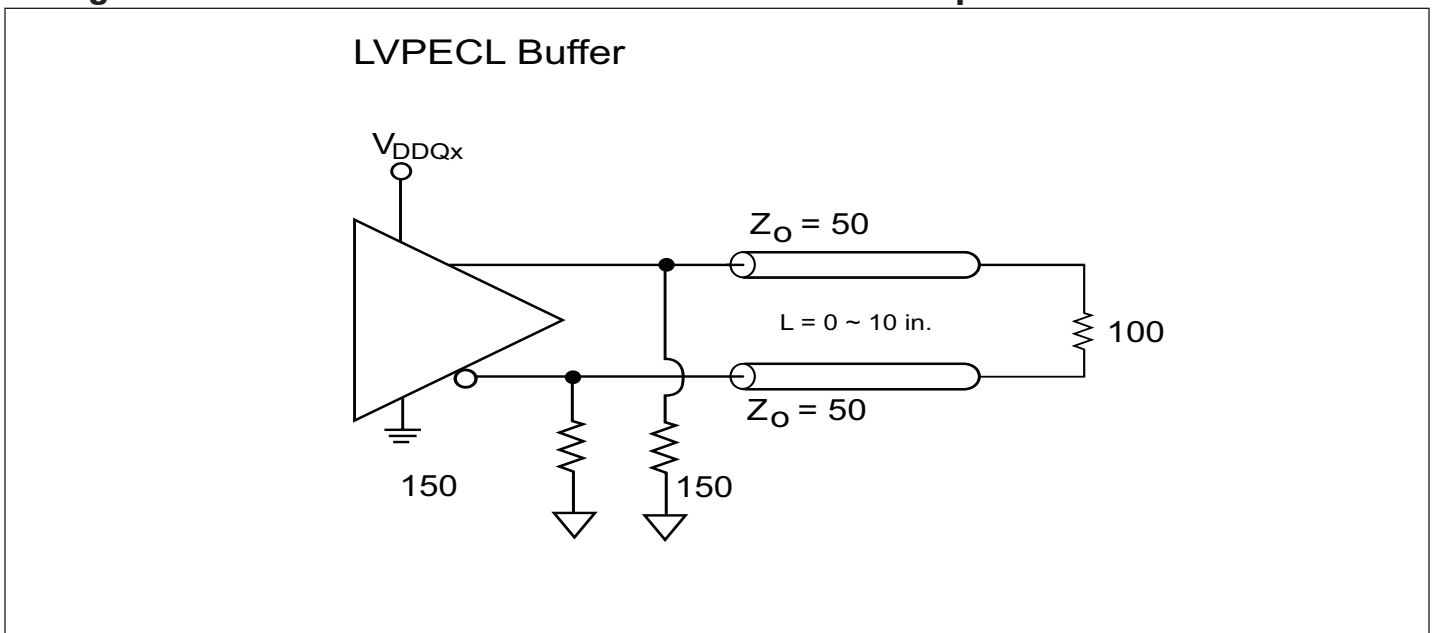
### Phase Noise and Additive Jitter

Output phase noise (Dark Blue) vs Input Phase noise (light blue)

Additive jitter is calculated at ~27fs RMS (12kHz to 20MHz). Additive jitter =  $\sqrt{(\text{Output jitter}^2 - \text{Input jitter}^2)}$



### Configuration Test Load Board Termination for LVPECL Outputs



**Application Information**

*Wiring the differential input to accept single ended levels*

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage  $V_{REF} = V_{DD}/2$  is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio of R1 and R2 might need to be adjusted to position the  $V_{REF}$  in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and  $V_{DD} = 3.3V$ ,  $V_{REF}$  should be 1.25V and  $R1/R2 = 0.609$ .

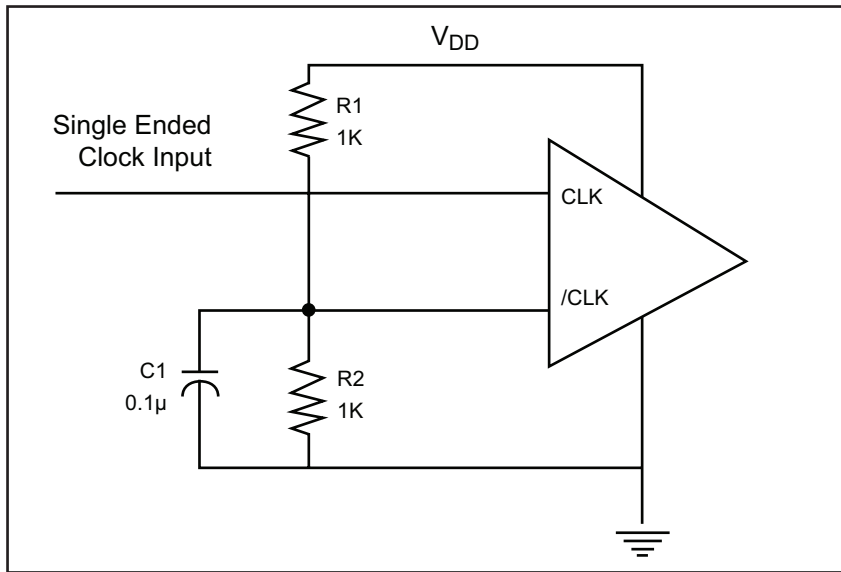
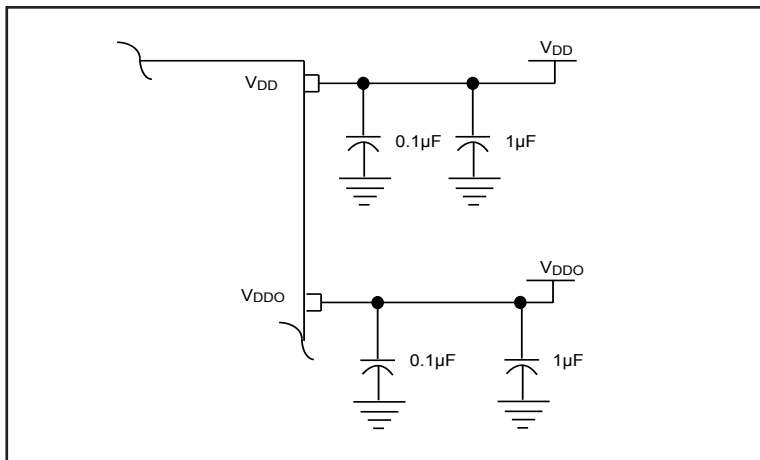
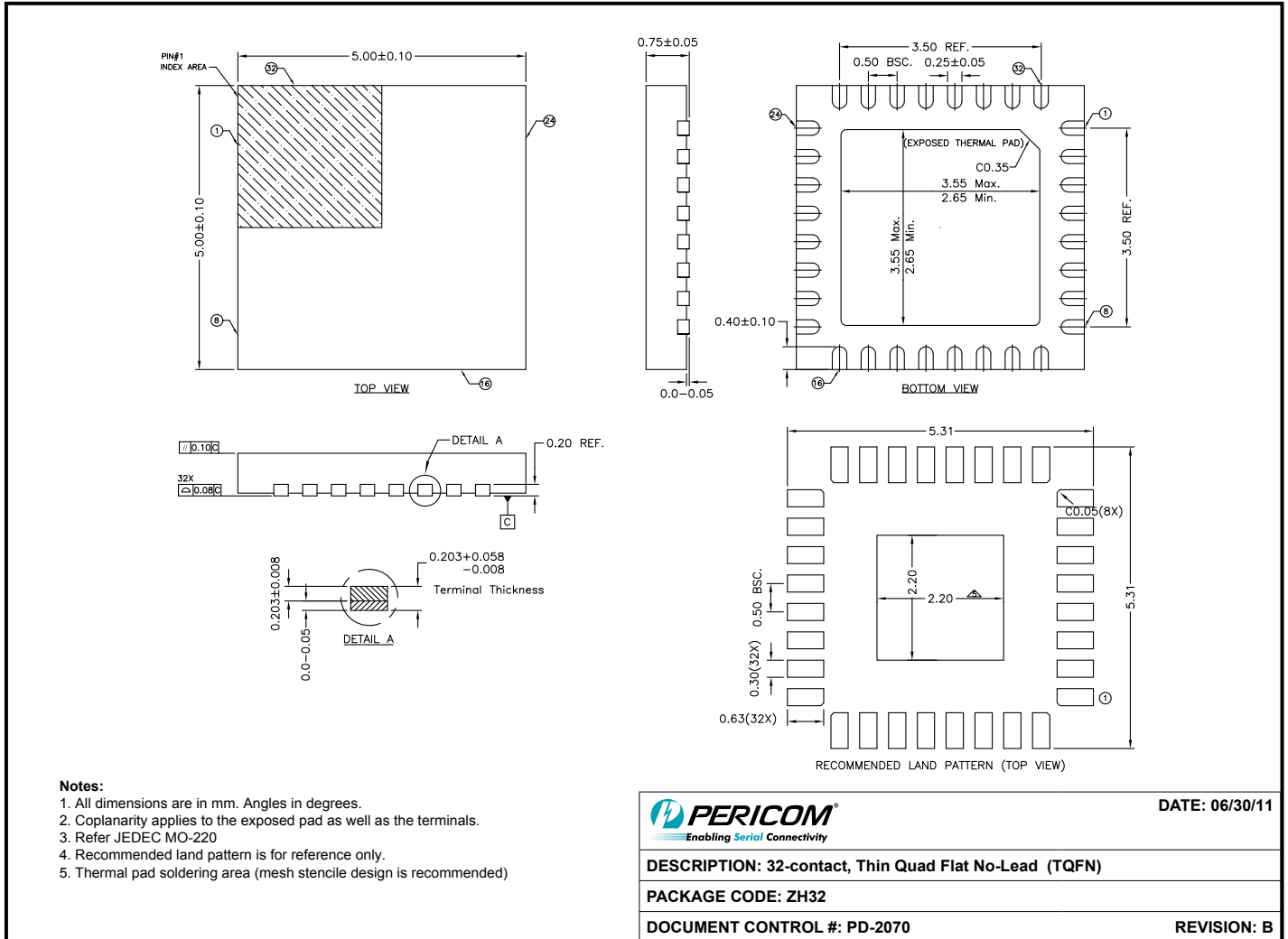


Figure 1. Single-ended input to Differential input device

**Power Supply Filtering Techniques**

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. To achieve optimum jitter performance, power supply isolation is required. All power pins should be individually connected to the power supply plane through vias, and 0.1µF and 1µF bypass capacitors should be used for each pin.



**Packaging Mechanical: 32-pin QFN (ZH)**


11-0147

**Thermal Information**

Symbol	Description	Condition	
$\Theta_{JA}$	Junction-to-ambient thermal resistance	Still air	44.70 °C/W
$\Theta_{JC}$	Junction-to-case thermal resistance		21.70 °C/W

**Packaging Mechanical: 32-pin TQFP (FA)**

**DOCUMENT CONTROL NO.**  
PD - 1814

**REVISION: C**  
**DATE: 03/09/05**

**Notes:**

- Controlling dimensions in millimeters
- Ref.: JEDEC MS-026D/ABA
- Package Outline Exclusive of Mold Flash and Metal Burr

**Pericom Semiconductor Corporation**  
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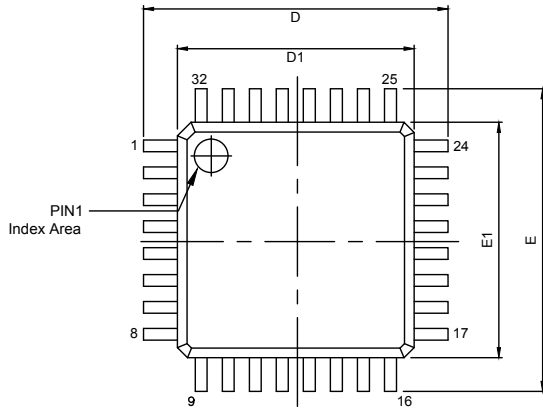
**DESCRIPTION: 32-Pin, Thin Quad Flat Package, TQFP**

**PACKAGE CODE: FA**

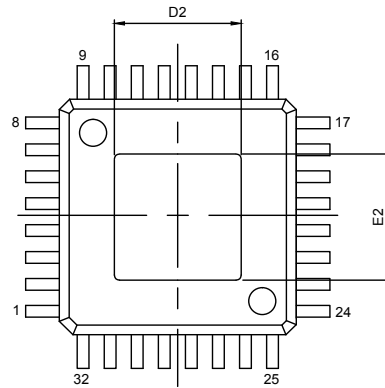
**Thermal Information**

Symbol	Description	Condition	
$\Theta_{JA}$	Junction-to-ambient thermal resistance	Still air	86 °C/W
$\Theta_{JC}$	Junction-to-case thermal resistance		12.7 °C/W

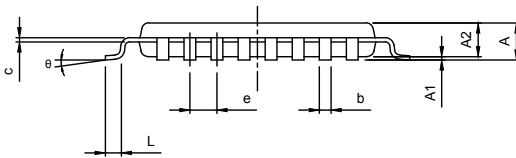


**Packaging Mechanical: 32-pin TQFP with E-Pad (FAE)**


TOP VIEW



BOTTOM VIEW



SIDE VIEW

PKG. DIMENSIONS(MM)		
SYMBOLS	MIN.	MAX.
A	-	1.20
A1	0.05	0.15
A2	0.95	1.05
b	0.30	0.45
c	0.09	0.20
D	8.75	9.25
D1	6.90	7.10
E	8.75	9.25
E1	6.90	7.10
e	0.80 BSC	
L	0.45	0.75
D2	3.19	3.90
E2	3.19	3.90
$\theta$	0°	7°

 NOTES:  
 1.Ref: JEDEC MS-026 ABA-HD


DATE: 03/24/15

DESCRIPTION: 32-Pin, TQFP, 7X7, Exposed Pad

PACKAGE CODE: FAE (FAE32)

DOCUMENT CONTROL #: PD-2196

REVISION: --

**Thermal Information**

Symbol	Description	Condition	
$\Theta_{JA}$	Junction-to-ambient thermal resistance	Still air	45 °C/W
$\Theta_{JC}$	Junction-to-case thermal resistance		15 °C/W

**Ordering Information(1,2,3)**

Ordering Code	Package Code	Package Description
PI6C4911510ZHIE	ZH	Pb-free & Green, 32-pin QFN
PI6C4911510ZHIEX	ZH	Pb-free & Green, 32-pin QFN, Tape & Reel
PI6C4911510FAIE	FA	Pb-free & Green, 32-pin TQFP
PI6C4911510FAIEX	FA	Pb-free & Green, 32-pin TQFP, Tape & Reel
PI6C4911510FAEIE	FAE	Pb-free & Green, 32-pin TQFP E-Pad
PI6C4911510FAEIEEX	FAE	Pb-free & Green, 32-pin TQFP E-Pad, Tape & Reel

**Notes:**

1. Thermal characteristics can be found on the company web site at [www.pericom.com/packaging/](http://www.pericom.com/packaging/)
2. E = Pb-free & Green
3. X suffix = Tape/Reel